

AN 1991:612994 CAPLUS <<LOGINID::20081025>>  
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 TI Copper alloy for backing plate of sputtering targets  
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 PA Sumitomo Metal Mining Co., Ltd., Japan; Sumitomo Kinzoku Kozan Shindo  
 Hanbai K. K.  
 SO Jpn. Kokai Tokkyo Koho, 4 pp.  
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 DT Patent  
 LA Japanese  
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	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 03072043	A	19910327	JP 1989-209381	19890811
	JP 2552920	B2	19961113		
PRAI	JP 1989-209381		19890811		
AB	The Cu alloy contains Fe 0.1-2.6, P 0.001-0.1, and optionally Sn 0.01-2.5, Mg 0.001-0.5, Zn, Co, Ni, and/or Te 0.01-1.0 each, and/or Pb 0.01-4.0%. The alloy shows a good thermal conductivity, solderability, and resistance to thermal strain, and is useful for backing plates in sputtering targets that can be recycled.				